



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-12-13
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMG Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**


<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TSV631IYLT	HYWY*V631BUY	A	ZS1A	2016-12-13
Amount		UoM	Unit type	ST ECOPACK Grade
16.38		mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		


  
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Package Designator	Size	Nbr of instances	Shape	
DSO	2.9- 1.6-1.05	5	gull wing	
Comment	Package: SOT 23-5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYWY*V631BUY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.425600349	mg	supplier	die	Silicon (Si)	7440-21-3		0.396	mg	930450	24176
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	8459	220
Silicon Die				supplier	metallization	Tin (Sn)	7440-31-5		0.004	mg	9398	244
Silicon Die				supplier	Passivation	Silicon Nitride (SiN)	68034-42-4		0.009	mg	21147	549
Silicon Die				supplier	Passivation	Silicon Oxide(SiO2)	7631-86-9		0.008	mg	18797	488
Silicon Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.005	mg	11748	305
Lead-frame	Copper & its alloys	7.197	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.933	mg	963318	423260
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.162	mg	22509	9890
Lead-frame				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	278	122
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1251	549
Lead-frame				supplier	metallization	Nickel (Ni)	7440-02-0		0.083	mg	11533	5067
Lead-frame				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	973	427
Lead-frame				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	139	61
Die Attach	Other Organic Material	0.07	mg	Supplier	Glue	Epoxyde Bisphenol A Resin	25068-38-6		0.02	mg	285714	1221
Die Attach				Supplier	Glue	Aromatic amine	Proprietary		0.003	mg	42857	183
Die Attach				Supplier	Glue	Glycol ether ester	Proprietary		0.003	mg	42857	183
Die Attach				Supplier	Glue	silica	60676-86-0		0.021	mg	300000	1282
Die Attach				Supplier	Glue	Aluminium oxide	1344-28-1		0.023	mg	328571	1404
Bonding Wire	Precious metals	0.15	mg	Supplier	Bonding Wire	Gold (Au)	7440-57-5		0.15	mg	1000000	9158
encapsulation	Other Inorganic Material	8.537	mg	supplier	mold compound	Silica, vitreous	60676-86-0		7.396	mg	866346	451526
encapsulation				supplier	mold compound	phenolic resin	9003-35-4		0.272	mg	31861	16606
encapsulation				supplier	mold compound	epoxy resin	90598-46-2		0.31	mg	36313	18926
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.155	mg	18156	9463
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.016	mg	1874	977
encapsulation				supplier	mold compound	Zinc hydroxide	20427-58-1		0.078	mg	9137	4762
encapsulation				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.31	mg	36313	18926